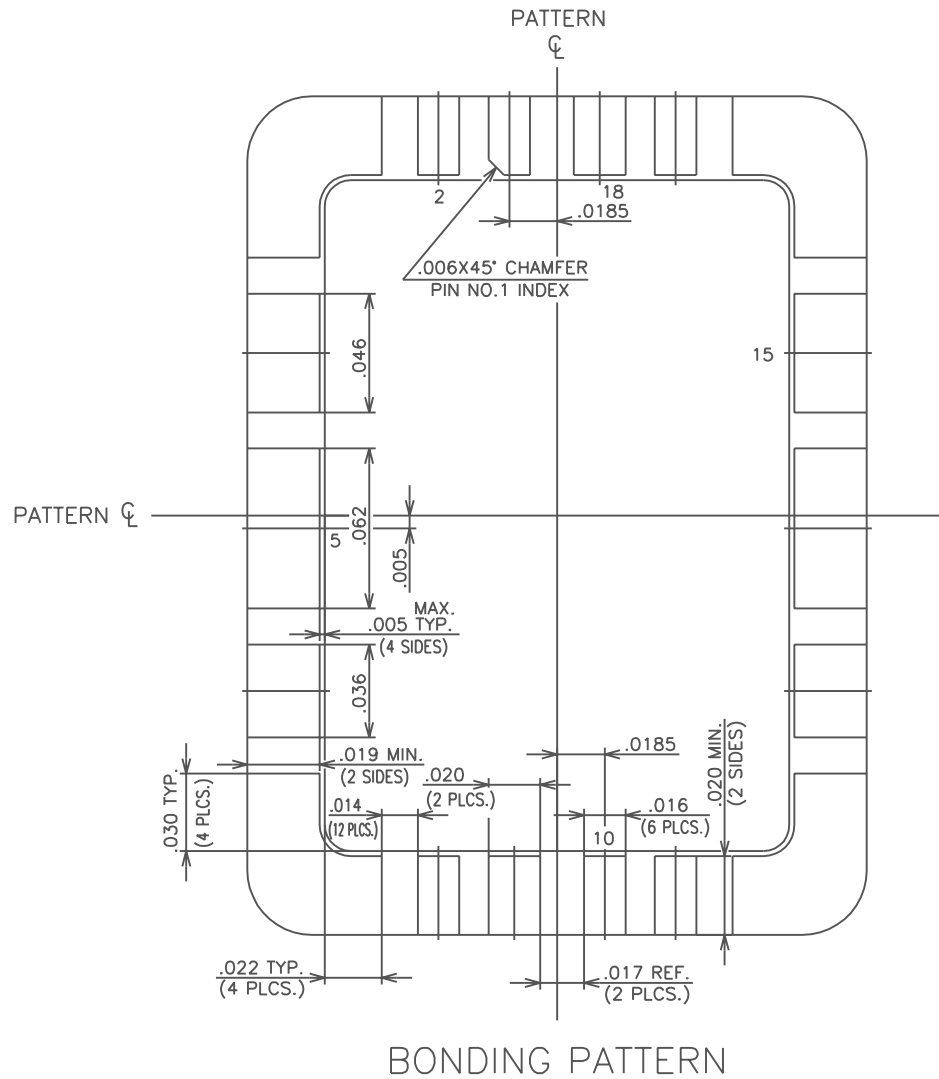


- NOTES :
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE MATTALLIZED.
 3. DIE ATTACH AREA TO BE MATTALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.5 OHM MAX.

MODIFICATION						NAME	TOLERANCE
						18 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED
						SCALE 5 / 1	MATERIAL
							AS INDICATED
							±1.0% NLT ±.005
							THIRD ANGLE PROJECTION
	REDRAWN:(CONVERTED CAD DATA.)	FEB.28.'00	H.K./Y.M	A.F./S.NI	H.SA		KYOCERA CORPORATION KYOTO JAPAN
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		

FB018N099-1				S=0
				D=0
DRAWN	CHECKED	APPROVED	DATE	
H.H	K.M		FEB.26.'00	
DRAWING NO.		SHEET		
KD-83099-A		1 / 2		





BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						18 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	H.H	K.M		FEB.26.'83
						SCALE 20/1					
						MATERIAL	THIRD ANGLE PROJECTION				
△	REDRAWN: (CONVERTED CAD DATA.)	FEB.28.'00	H.K/Y.M	A.F/S.NI	H.SA		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-83099-A	2/2		

